

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT												
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>BYUNG CHUL KANG</td> <td>11/30/2007</td> </tr> <tr> <td>KWANG DUCK KOH</td> <td>11/30/2007</td> </tr> <tr> <td>JUM DONG LEE</td> <td>11/30/2007</td> </tr> <tr> <td>HWA SEOB LEE</td> <td>11/30/2007</td> </tr> <tr> <td>JAE MOO SHIN</td> <td>11/30/2007</td> </tr> </tbody> </table>		Name	Execution Date	BYUNG CHUL KANG	11/30/2007	KWANG DUCK KOH	11/30/2007	JUM DONG LEE	11/30/2007	HWA SEOB LEE	11/30/2007	JAE MOO SHIN	11/30/2007
Name	Execution Date												
BYUNG CHUL KANG	11/30/2007												
KWANG DUCK KOH	11/30/2007												
JUM DONG LEE	11/30/2007												
HWA SEOB LEE	11/30/2007												
JAE MOO SHIN	11/30/2007												
<b>RECEIVING PARTY DATA</b>													
<b>Name:</b>	HYNIX SEMICONDUCTOR INC.												
<b>Street Address:</b>	San 136-1, Ami-ri, Bubal-eub, Icheon-si												
<b>City:</b>	Kyongki-do												
<b>State/Country:</b>	KOREA, REPUBLIC OF												
<b>PROPERTY NUMBERS Total: 1</b>													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11954368</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11954368								
Property Type	Number												
Application Number:	11954368												
<b>CORRESPONDENCE DATA</b>													
<b>Fax Number:</b>	(312)427-6663												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
<b>Phone:</b>	3124271300												
<b>Email:</b>	nicholas.kubacki@ladas.net												
<b>Correspondent Name:</b>	RICHARD J. STREIT												
<b>Address Line 1:</b>	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.												
<b>Address Line 4:</b>	CHICAGO, ILLINOIS 60604												
<b>ATTORNEY DOCKET NUMBER:</b>	CU-6248 WWP/NK												
<b>NAME OF SUBMITTER:</b>	Woochoon W. Park												
<b>Total Attachments: 2</b> source=cu6248assign#page1.tif													

**CH \$40.00 11954368**



---

**UNITED STATES OF AMERICA**  
**ASSIGNMENT**

---

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

**ASSIGNOR:**

Name : Byung Chul KANG

Address : 302-1703, Hyundai Apt., Ami 3-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

Name: Kwang Duck KOH

Address: #803, Ssangyong Apt., Nonhyeon-dong, Gangnam-gu, Seoul, Korea

Name: Jum Dong LEE

Address: 103-1005, Hyundai Apt., 441-1, Sadong-ri, Daewol-myeon, Icheon-si, Gyeonggi-do, Korea

Name: Hwa Seob LEE

Address: 1511-1302, Hanareum Apt., Sang-dong, Wonmi-gu, Bucheon-si, Gyeonggi-do, Korea

Name: Jae Moo SHIN

Address: 104-109, Samick Apt., Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

**ASSIGNEE:**

**Name : Hynix Semiconductor Inc.**

**Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea**

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

SEMICONDUCTOR DIE BONDING APPARATUS HAVING MULTIPLE BONDING HEAD UNITS

(TITLE)

and which is found in *(check one applicable item below)*

U.S. patent application executed on even date herewith

U.S. Application Serial No. \_\_\_\_\_ filed on \_\_\_\_\_

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

November 30, 2007

Date

*Byung Chul KANG*

INVENTOR: Byung Chul KANG

November 30, 2007

Date

*K. D. Koh*

INVENTOR: Kwang Duck KOH

November 30, 2007

Date

*Jum Dong LEE*

INVENTOR: Jum Dong LEE

November 30, 2007

Date

*Hwa Seob LEE*

INVENTOR: Hwa Seob LEE

November 30, 2007

Date

*Jae Moo Shim*

INVENTOR: Jae Moo SHIN

0699P/1

PATENT

RECORDED: 12/12/2007

REEL: 020231 FRAME: 0493